PC364NJ0000F Series

Mini-Flat Package
High CMR, AC Input, Low Input Current Type Photocoupler

■ Description
PC364NJ0000F Series contains an IRED optically coupled to a phototransistor.
AC input and Low input current type.
It is packaged in a 4-pin mini-flat.
Input-output isolation voltage (rms) is 3.75kV.
Collector-emitter voltage is 80V and CTR is 50% to 400% at input current of ±0.5mA.

■ Features
1. 4-pin Mini-flat package
2. Double transfer mold package (Ideal for Flow Soldering)
3. AC input type
4. Low input current type (I<sub>f</sub>=±0.5mA)
5. High collector-emitter voltage (V<sub>CEO</sub> : 80V)
6. High noise immunity due to high common mode rejection voltage (CMR : MIN. 10kV/μs)
7. High isolation voltage between input and output (V<sub>iso(rms)</sub> : 3.75kV)
8. RoHS directive compliant

■ Agency approvals/Compliance
1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC364)
2. Package resin : UL flammability grade (94V-0)

■ Applications
1. Programmable controllers
2. Facsimiles
3. Telephones

Notice The content of data sheet is subject to change without prior notice.
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### Internal Connection Diagram

1. Anode/Cathode
2. Cathode/Anode
3. Emitter
4. Collector

### Outline Dimensions

(Unit: mm)

- **SHARP mark “S”**
- **Primary side mark**
- **Date code**
- **Rank mark**
- **Factory identification mark**
- **Epoxy resin**

- **Product mass**: approx. 0.1g

**Plating material**: SnCu (Cu: TYP. 2%)
### Date code (2 digit)

<table>
<thead>
<tr>
<th>Year of production</th>
<th>Month of production</th>
<th>Mark</th>
<th>A.D.</th>
<th>Mark</th>
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<td>A</td>
<td>2002</td>
<td>P</td>
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<td>1991</td>
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<td>1995</td>
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<td>2001</td>
<td>N</td>
<td></td>
<td></td>
<td>December</td>
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Repeats in a 20 year cycle.

### Factory identification mark

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<th>Factory identification Mark</th>
<th>Country of origin</th>
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<tr>
<td>![Symbol]</td>
<td>Indonesia</td>
</tr>
<tr>
<td>![Symbol]</td>
<td>China</td>
</tr>
</tbody>
</table>

*This factory marking is for identification purpose only. Please Contact the local SHARP sales representative to see the actual status of the production.*

### Rank mark

Refer to the Model Line-up table.
## Absolute Maximum Ratings  
(T<sub>a</sub>=25°C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Rating</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Forward current</td>
<td>IF</td>
<td>±10</td>
<td>mA</td>
</tr>
<tr>
<td>*1 Peak forward current</td>
<td>IFM</td>
<td>±200</td>
<td>mA</td>
</tr>
<tr>
<td>Power dissipation</td>
<td>P</td>
<td>15</td>
<td>mW</td>
</tr>
<tr>
<td>Collector-emitter voltage</td>
<td>V&lt;sub&gt;CBO&lt;/sub&gt;</td>
<td>80</td>
<td>V</td>
</tr>
<tr>
<td>Emitter-collector voltage</td>
<td>V&lt;sub&gt;EBO&lt;/sub&gt;</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Collector current</td>
<td>I&lt;sub&gt;C&lt;/sub&gt;</td>
<td>50</td>
<td>mA</td>
</tr>
<tr>
<td>Collector power dissipation</td>
<td>P&lt;sub&gt;C&lt;/sub&gt;</td>
<td>150</td>
<td>mW</td>
</tr>
<tr>
<td>Total power dissipation</td>
<td>P&lt;sub&gt;tot&lt;/sub&gt;</td>
<td>170</td>
<td>mW</td>
</tr>
<tr>
<td>Operating temperature</td>
<td>T&lt;sub&gt;oper&lt;/sub&gt;</td>
<td>−30 to +100</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>T&lt;sub&gt;stg&lt;/sub&gt;</td>
<td>−40 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>*2 Isolation voltage</td>
<td>V&lt;sub&gt;iso(rms)&lt;/sub&gt;</td>
<td>3.75</td>
<td>kV</td>
</tr>
<tr>
<td>*3 Soldering temperature</td>
<td>T&lt;sub&gt;sol&lt;/sub&gt;</td>
<td>260</td>
<td>°C</td>
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</table>

*1 Pulse width≤100µs, Duty ratio : 0.001  
*2 40 to 60%RH, AC for 1 minute, f=60Hz  
*3 For 10s

## Electro-optical Characteristics  
(T<sub>a</sub>=25°C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>MIN.</th>
<th>TYP.</th>
<th>MAX.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Forward voltage</td>
<td>V&lt;sub&gt;F&lt;/sub&gt;</td>
<td>IF=±10mA</td>
<td>–</td>
<td>1.2</td>
<td>1.4</td>
<td>V</td>
</tr>
<tr>
<td>Terminal capacitance</td>
<td>C&lt;sub&gt;t&lt;/sub&gt;</td>
<td>V=0, f=1kHz</td>
<td>–</td>
<td>30</td>
<td>250</td>
<td>pF</td>
</tr>
<tr>
<td>Collector dark current</td>
<td>I&lt;sub&gt;CBO&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CBO&lt;/sub&gt;=50V, IF=0</td>
<td>–</td>
<td>–</td>
<td>100</td>
<td>nA</td>
</tr>
<tr>
<td>Collector-emitter breakdown voltage</td>
<td>BV&lt;sub&gt;CBO&lt;/sub&gt;</td>
<td>I&lt;sub&gt;C&lt;/sub&gt;=0.1mA, IF=0</td>
<td>80</td>
<td>–</td>
<td>–</td>
<td>V</td>
</tr>
<tr>
<td>Emitter-collector breakdown voltage</td>
<td>BV&lt;sub&gt;EBO&lt;/sub&gt;</td>
<td>I&lt;sub&gt;E&lt;/sub&gt;=10µA, IF=0</td>
<td>6</td>
<td>–</td>
<td>–</td>
<td>V</td>
</tr>
<tr>
<td>Collector current</td>
<td>I&lt;sub&gt;C&lt;/sub&gt;</td>
<td>IF=±0.5mA, V&lt;sub&gt;CBO&lt;/sub&gt;=5V</td>
<td>0.25</td>
<td>–</td>
<td>2.0</td>
<td>mA</td>
</tr>
<tr>
<td>Collector-emitter saturation voltage</td>
<td>BV&lt;sub&gt;CBO&lt;/sub&gt;</td>
<td>IF=±10mA, IC=1mA</td>
<td>–</td>
<td>–</td>
<td>0.2</td>
<td>V</td>
</tr>
<tr>
<td>Isolation resistance</td>
<td>R&lt;sub&gt;SIO&lt;/sub&gt;</td>
<td>DC500V, 40 to 60%RH</td>
<td>5x10&lt;sup&gt;10&lt;/sup&gt;</td>
<td>1x10&lt;sup&gt;11&lt;/sup&gt;</td>
<td>–</td>
<td>Ω</td>
</tr>
<tr>
<td>Floating capacitance</td>
<td>C&lt;sub&gt;f&lt;/sub&gt;</td>
<td>V=0, f=1MHz</td>
<td>–</td>
<td>0.6</td>
<td>1.0</td>
<td>pF</td>
</tr>
<tr>
<td>Response time Rise time</td>
<td>t&lt;sub&gt;r&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CBO&lt;/sub&gt;=2V, I&lt;sub&gt;C&lt;/sub&gt;=2mA, R&lt;sub&gt;L&lt;/sub&gt;=100Ω</td>
<td>–</td>
<td>4</td>
<td>18</td>
<td>µs</td>
</tr>
<tr>
<td>Response time Fall time</td>
<td>t&lt;sub&gt;f&lt;/sub&gt;</td>
<td>–</td>
<td>–</td>
<td>3</td>
<td>18</td>
<td>µs</td>
</tr>
<tr>
<td>Common mode rejection voltage</td>
<td>CMR</td>
<td>T&lt;sub&gt;a&lt;/sub&gt;=25°C, R&lt;sub&gt;L&lt;/sub&gt;=470Ω, V&lt;sub&gt;CM&lt;/sub&gt;=1.5kV(peak) IF=0, V&lt;sub&gt;CC&lt;/sub&gt;=9V, V&lt;sub&gt;ap&lt;/sub&gt;=100mV</td>
<td>10</td>
<td>–</td>
<td>–</td>
<td>kV/µs</td>
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</table>
## Model Line-up

<table>
<thead>
<tr>
<th>Package</th>
<th>Taping</th>
<th>Rank mark</th>
<th>IC [mA] (I_p=±0.5mA, V_CE=5V, T_a=25°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>PC364NJ0000F</td>
<td>3 000 pcs / reel</td>
<td>with or without</td>
<td>0.25 to 2.0</td>
</tr>
<tr>
<td>PC364N1J000F</td>
<td>750 pcs / reel</td>
<td>A</td>
<td>0.5 to 1.5</td>
</tr>
</tbody>
</table>

Please contact a local SHARP sales representative to inquire about production status.
Fig. 1 Test Circuit for Common Mode Rejection Voltage

Fig. 2 Forward Current vs. Ambient Temperature

Fig. 3 Diode Power Dissipation vs. Ambient Temperature

Fig. 4 Collector Power Dissipation vs. Ambient Temperature

Fig. 5 Total Power Dissipation vs. Ambient Temperature
**Fig. 6 Peak Forward Current vs. Duty Ratio**

- **Duty ratio** vs. **Peak forward current IpM (mA)**

**Fig. 7 Forward Current vs. Forward Voltage**

- **Forward voltage Vf (V)** vs. **Forward current If (mA)**

**Fig. 8 Current Transfer Ratio vs. Forward Current**

- **Forward current If (mA)** vs. **Current transfer ratio CTR (%)**

**Fig. 9 Collector Current vs. Collector-emitter Voltage**

- **Collector-emitter voltage Vce (V)** vs. **Collector current Ic (mA)**

**Fig. 10 Relative Current Transfer Ratio vs. Ambient Temperature**

- **Ambient temperature Ta (°C)** vs. **Relative current transfer ratio (%)**

**Fig. 11 Collector - emitter Saturation Voltage vs. Ambient Temperature**

- **Collector-emitter saturation voltage Vce (V)** vs. **Ambient temperature Ta (°C)**
Fig.12 Collector Dark Current vs. Ambient Temperature

Fig.13 Response Time vs. Load Resistance (Active region)

Fig.14 Response Time vs. Load Resistance (Saturation region)

Fig.15 Test Circuit for Response Time

Fig.16 Frequency Response

Fig.17 Collector-emitter Saturation Voltage vs. Forward Current

Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.
Design Considerations

- Design guide
  While operating at I_F<0.5mA, CTR variation may increase. Please make design considering this fact.

  In case that some sudden big noise caused by voltage variation is provided between primary and secondary terminals of photocoupler some current caused by it is floating capacitance may be generated and result in false operation since current may go through IRED or current may change. If the photocoupler may be used under the circumstances where noise will be generated we recommend to use the bypass capacitors at the both ends of IRED.

  This product is not designed against irradiation and incorporates non-coherent IRED.

- Degradation
  In general, the emission of the IRED used in photocouplers will degrade over time. In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

- Recommended Foot Print (reference)

  (Unit : mm)

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.
Manufacturing Guidelines

● Soldering Method

Reflow Soldering:
Reflow soldering should follow the temperature profile shown below.
Soldering should not exceed the curve of temperature profile and time.
Please don't solder more than twice.

Flow Soldering:
Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.
Flow soldering should be completed below 260°C and within 10s.
Preheating is within the bounds of 100 to 150°C and 30 to 80s.
Please don't solder more than twice.

Hand soldering
Hand soldering should be completed within 3s when the point of solder iron is below 400°C.
Please don't solder more than twice.

Other notices
Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.
● **Cleaning instructions**

**Solvent cleaning:**
Solvent temperature should be 45°C or below Immersion time should be 3 minutes or less

**Ultrasonic cleaning:**
The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device. Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

**Recommended solvent materials:**
Ethyl alcohol, Methyl alcohol and Isopropyl alcohol
In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● **Presence of ODC**

This product shall not contain the following materials.
And they are not used in the production process for this product.
Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).
  • Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
Package specification
• Tape and Reel package
  1. 3,000pcs/reel
Package materials
  Carrier tape: A-PET (with anti-static material)
  Cover tape: PET (three layer system)
  Reel: PS
Carrier tape structure and Dimensions

Dimensions List (Unit: mm)

<table>
<thead>
<tr>
<th></th>
<th>A</th>
<th>B</th>
<th>C</th>
<th>D</th>
<th>E</th>
<th>F</th>
<th>G</th>
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<tbody>
<tr>
<td>H</td>
<td>12.0±0.3</td>
<td>5.5±0.1</td>
<td>1.75±0.1</td>
<td>8.0±0.1</td>
<td>2.0±0.1</td>
<td>4.0±0.1</td>
<td>φ1.5±0.1</td>
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<tr>
<td>I</td>
<td>7.4±0.1</td>
<td>0.3±0.05</td>
<td>3.1±0.1</td>
<td>4.0±0.1</td>
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Reel structure and Dimensions

Dimensions List (Unit: mm)

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<th>a</th>
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<tbody>
<tr>
<td>a</td>
<td>370</td>
<td>13.5±1.5</td>
<td>80±1.0</td>
<td>13±0.5</td>
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<tr>
<td>e</td>
<td>21±1.0</td>
<td>2.0±0.5</td>
<td>2.0±0.5</td>
<td></td>
</tr>
</tbody>
</table>

Direction of product insertion

Pull-out direction

[Packing: 3,000pcs/reel]
Package materials
2. 750 pcs / reel
Carrier tape : A-PET (with anti-static material)
Cover tape : PET (three layer system)
Reel : PS

Carrier tape structure and Dimensions

Reel structure and Dimensions

Direction of product insertion

Dimensions List
(Unit : mm)

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PC364NJ0000F Series
**Important Notices**

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  (i) The devices in this publication are designed for use in general electronic equipment designs such as:
      --- Personal computers
      --- Office automation equipment
      --- Telecommunication equipment [terminal]
      --- Test and measurement equipment
      --- Industrial control
      --- Audio visual equipment
      --- Consumer electronics
  
  (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
      --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
      --- Traffic signals
      --- Gas leakage sensor breakers
      --- Alarm equipment
      --- Various safety devices, etc.

  (iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
      --- Space applications
      --- Telecommunication equipment [trunk lines]
      --- Nuclear power control equipment
      --- Medical and other life support equipment (e.g., scuba).

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